

# MADASU SAI TEJA

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**Address:** Nacharam, Hyderabad | **Contact no:** 9440370914\6301534643 | **Email:**steja1267@gmail.com

## Career Objective

To work in a challenging position in a growth Oriented Company and contribute to its development as well as of mine.

## Education

### **B-TECH | 2025 | MALLA REDDY ENGINEERING COLLEGE AND MANAGEMENT SCIENCES**

- Stream: Electrical and Electronics Engineering (EEE)
- Major Project: Automatic power factor correction and monitoring using IOT.
- Minor Project: power failure and fault detection system.

### **DIPLOMA | 2022 | THEEGALA KRISHNA REDDY (TKR) ENGINEERING COLLEGE.**

- Stream: Electrical and Electronics Engineering (EEE).
- Major project Title: Installation of Solar panel using inverter and batteries
- Industrial training: I got certified in south central railway, Lalaguda carriage workshop for six months

### **SSC | 2019 | KAMALA MEMORIAL HIGH SCHOOL**

## Experience

- TECHNICAL SUPPORT ENGINEER | Defence Research and Development Laboratory (DRDO/RCI) | Dates From 02-may-2022- To 10-july-2025
- Functional testing of PCB's used for IMU and INS.
- Unit level testing - Involved in Isolation checks, Functional test, Calibration, Navigation runs, QT/AT which includes environment tests such as vibration, temperature cycling, shock, damp heat, EMI/EMC tests
- Direct current-Direct current Module (DC-DC) load test.
- PCB layout and Gerber verification according to the schematics.
- Preparation and verification of BOM according to the schematics.
- Experience on troubleshooting and analyzing the failure criteria of board level testing.
- Tuning of VTOF cards and soldering of PCB cards.
- Operation of different equipment's like Multimeter, Oscilloscopes, Function generator, Rate table simulators and temperature chambers.
- CEMILAC screening (Stabilization, Thermal shock and Power burn-in) tests of following PCB's.
- Three Gyro Single Processing Board (TGSP).
- Digital Signal Conditioning Card (DSC).
- Navigations card (NC).
- Loading of Bit, MCS and Bin files into FPGA, and Processor boards using Xilinx and Flash loader software In populated PCB

- Involved in System Integration of INS.
- Report generation for QC clearance and document (QAP) preparation.
- Support in R&D activities.
- Using application's mat-lab, c, impact, real term.

## **Skills & Abilities**

### **MANAGEMENT**

- Successfully led cross-functional teams to deliver projects on time and within budget.
- Skilled in scheduling, task delegation, and performance monitoring.
- Experienced in process improvement and workflow optimization to increase efficiency.
- Balanced academic studies (B.Tech) alongside full-time technical responsibilities.

### **LEADERSHIP**

- Served as team lead for a company-wide training initiative, improving onboarding efficiency by 30%.
- Mentored junior staff, fostering growth and increasing team retention rates.
- Took initiative in organizing volunteer events, driving team engagement and community impact.

### **COMMUNICATION**

- Strong interpersonal skills with experience collaborating across departments and cultural backgrounds.

### **Personal Details:**

Name : MADASU SAI TEJA

FATHER NAME : MADASU KRISHNA

DATE OF BIRTH : 14th June 2003

LANGUAGES KNOWN : Telugu, Hindi, English.